

5. (Allowed)

6. (Currently Amended) The An aqueous emulsion ~~type~~ photosolder resist composition ~~according to claim 1, wherein~~ obtained by neutralizing said resin (A) according to claim 1 ~~is~~ neutralized by with a base and ~~made to be~~ water-soluble.

7. (Currently Amended) The aqueous emulsion ~~type~~ photosolder resist composition according to claim 6, wherein said resin (A) has double bonds of 0.1×10^{-3} to 3.0×10^{-3} mol/g and the content of the carboxyl group of 30 to 200 mgKOH/g.

8. (Currently Amended) The aqueous emulsion ~~type~~ photosolder resist composition according to claim 6, wherein the ratio of the carboxyl group in said resin (A) and the cyclic ether group in said photocurable mixture (C) is (1.3/0.7) to (0.7/1.3) by mole ratio.

9. (Currently Amended) The aqueous emulsion ~~type~~ photosolder resist composition according to ~~claims~~ claim 6, further containing a coloring pigment.

10. (Currently Amended) The aqueous emulsion ~~type~~ photosolder resist composition according to claim 6, wherein the content of said inorganic filler (B) is 5 to 75 parts by weight in 100 parts by weight of solid content of the entire photosolder resist composition.

11. (Allowed)

12. (Withdrawn)